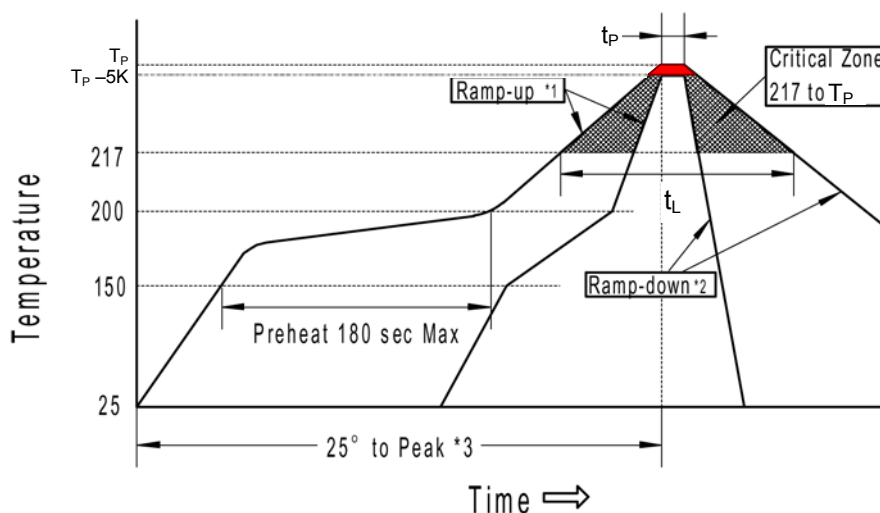


LEAD-FREE REFLOW SOLDERING CONDITIONS

1. A thermal condition system such as infrared radiation (IR) or hot blast should be adopted, and vapor heat transfer systems (VPS) are not recommended.
2. Reflow soldering should be performed only one time.
3. Please follow following conditions for reflow soldering:
 - The time of preheating from 150°C to 200°C shall be within 180 seconds maximum;
 - The time of soldering temperature at 217°C and more measured on capacitors top shall not exceed t_L (second);
 - The peak temperature on capacitors top shall not exceed T_P (°C).
 - The maximum time within a 5K area below T_P (°C) shall not exceed t_p (second) (in diagram marked in red color).

• Reflow Soldering Profile



*1. Average ramp-up rate is 3°C/second max.

*2. Ramp-down rate is 6°C/second max.

*3. Time from 25°C to peak temperature is 8 minutes max.

• Classified at Temperature and Time

Size	Thickness (mm) Soldering paste	T_P (°C)	t_L (second)	t_p (second)
Ø8x11.8	≥ 2.5	240 ±0	90	30
Ø10x12.7	≥ 2.5	235 ±0	60	30